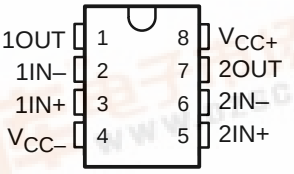
DUAL LOW-NOISE HIGH-DRIVE OPERATIONAL AMPLIFIER

SLVS457A – JANUARY 2003 – REVISED MARCH 2003

- **Equivalent Input Noise Voltage 5 nV/√Hz Typ at 1 kHz**
- **Unity-Gain Bandwidth . . . 10 MHz Typ**
- **High Slew Rate . . . 9 V/μs Typ**
- **Peak-to-Peak Output Voltage Swing 32 V Typ, With $V_{CC\pm}$ = ±18 V and R_L = 600 Ω**
- **Wide Supply-Voltage Range . . . ±3 V to ±20 V**
- **Common-Mode Rejection Ratio . . . 100 dB Typ**
- **High dc Voltage Gain . . . 100 V/mV Typ**
- **Applications: Audio PreAmps, Active Filters, Headphone Amps**
- **End Equipment: DVD/CD/CDRW Players; Set-Top Boxes**

D, P, OR PS PACKAGE
(TOP VIEW)



description/ordering information

The TL4581 is a dual operational amplifier that has been designed optimally for audio applications, such as improving tone control. It offers low noise, high-gain bandwidth, good slew, and high output current drive for driving capacitive loads. These features make the TL4581 ideally suited for audio applications, such as audio preamps and active filters. When high output current is required, the TL4581 also can be used as a headphone amplifier.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – P	Tube of 50	TL4581P	TL4581P
	SOIC – D	Tube of 75	TL4581D	T4581
		Reel of 2500	TL4581DR	
	SOP – PS	Reel of 2000	TL4581PSR	T4581

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage (see Note 1): V_{CC+} . . . . . 22 V
$V_{CC–}$ . . . . . –22 V
Input voltage, either input (see Notes 1 and 2) . . . . . $V_{CC±}$
Input current (see Note 3) . . . . . ±10 mA
Duration of output short circuit (see Note 4) . . . . . Unlimited
Operating virtual junction temperature, T_J . . . . . 150°C
Package thermal impedance, θ_{JA} (see Notes 5 and 6): D package . . . . . 97°C/W
P package . . . . . 85°C/W
PS package . . . . . 95°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 260°C
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and $V_{CC–}$.
2. The magnitude of the input voltage must never exceed the magnitude of the supply voltage.
3. Excessive input current will flow if a differential input voltage in excess of approximately 0.6 V is applied between the inputs, unless some limiting resistance is used.
4. The output may be shorted to ground or either power supply. Temperature and/or supply voltages must be limited to ensure the maximum dissipation rating is not exceeded.
5. Maximum power dissipation is a function of $T_J(max)$, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) – T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
6. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		MIN	MAX	UNIT
V_{CC+}	Supply voltage	5	15	V
$V_{CC–}$	Supply voltage	–5	–15	V
T_A	Operating free-air temperature range	0	70	°C

electrical characteristics, $V_{CC\pm}$ = +15 V, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS†			MIN	TYP	MAX	UNIT
V_{IO}	Input offset voltage	V_O = 0	T_A = 25°C			0.5	4	mV
			T_A = 0°C to 70°C				5	
I_{IO}	Input offset current	T_A = 25°C				10	150	nA
		T_A = 0°C to 70°C					200	
I_{IB}	Input bias current	T_A = 25°C				200	800	nA
		T_A = 0°C to 70°C					1000	
V_{ICR}	Common-mode input-voltage range				±12	±13		V
V_{OPP}	Maximum peak-to-peak output-voltage swing	R_L ≥ 600 Ω	$V_{CC\pm}$ = ±15 V		24	26		V
			$V_{CC\pm}$ = ±18 V		30	32		
A_{VD}	Large-signal differential-voltage amplification	R_L ≥ 600 Ω, V_O = ±10 V	T_A = 25°C		15	50		V/mV
			T_A = 0°C to 70°C		10			
		R_L ≥ 2 kΩ, V_O = ±10 V	T_A = 25°C		25	100		
			T_A = 0°C to 70°C		15			
A_{vd}	Small-signal differential-voltage amplification	f = 10 kHz				2.2		V/mV
B_{OM}	Maximum-output-swing bandwidth	R_L = 600 Ω	V_O = ±10 V			140		kHz
			$V_{CC\pm}$ = ±18 V,	V_O = ±14 V		100		
B_1	Unity-gain bandwidth	R_L = 600 Ω,	C_L = 100 pF			10		MHz
r_i	Input resistance				30	300		kΩ
z_o	Output impedance	A_{VD} = 30 dB,	R_L = 600 Ω,	f = 10 kHz		0.3		Ω
CMRR	Common-mode rejection ratio	V_{IC} = V_{ICR} min			70	100		dB
k_{SVR}	Supply-voltage rejection ratio ($\Delta V_{CC\pm}/\Delta V_{IO}$)	$V_{CC\pm}$ = ±9 V to ±15 V,		V_O = 0	80	100		dB
I_{OS}	Output short-circuit current				10	38	60	mA
I_{CC}	Total supply curent	V_O = 0,	No load			8	16	mA
	Crosstalk attenuation (V_{O1}/V_{O2})	V_{01} = 10 V peak,	f = 1 kHz			110		dB

† All characteristics are measured under open-loop conditions with zero common-mode input voltage, unless otherwise specified.

operating characteristics, $V_{CC\pm}$ = ±15 V, T_A = 25°C

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
SR	Slew rate at unity gain					9		V/μs
	Overshoot factor	V_I = 100 mV, R_L = 600 Ω,		A_{VD} = 1, C_L = 100 pF		10		%
V_n	Equivalent input noise voltage	f = 30 Hz				8		nV/√Hz
		f = 1 kHz				5		
I_n	Equivalent input noise current	f = 30 Hz				2.7		pA/√Hz
		f = 1 kHz				0.7		

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
TL4581D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL4581DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL4581DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL4581DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL4581P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL4581PE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL4581PSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL4581PSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

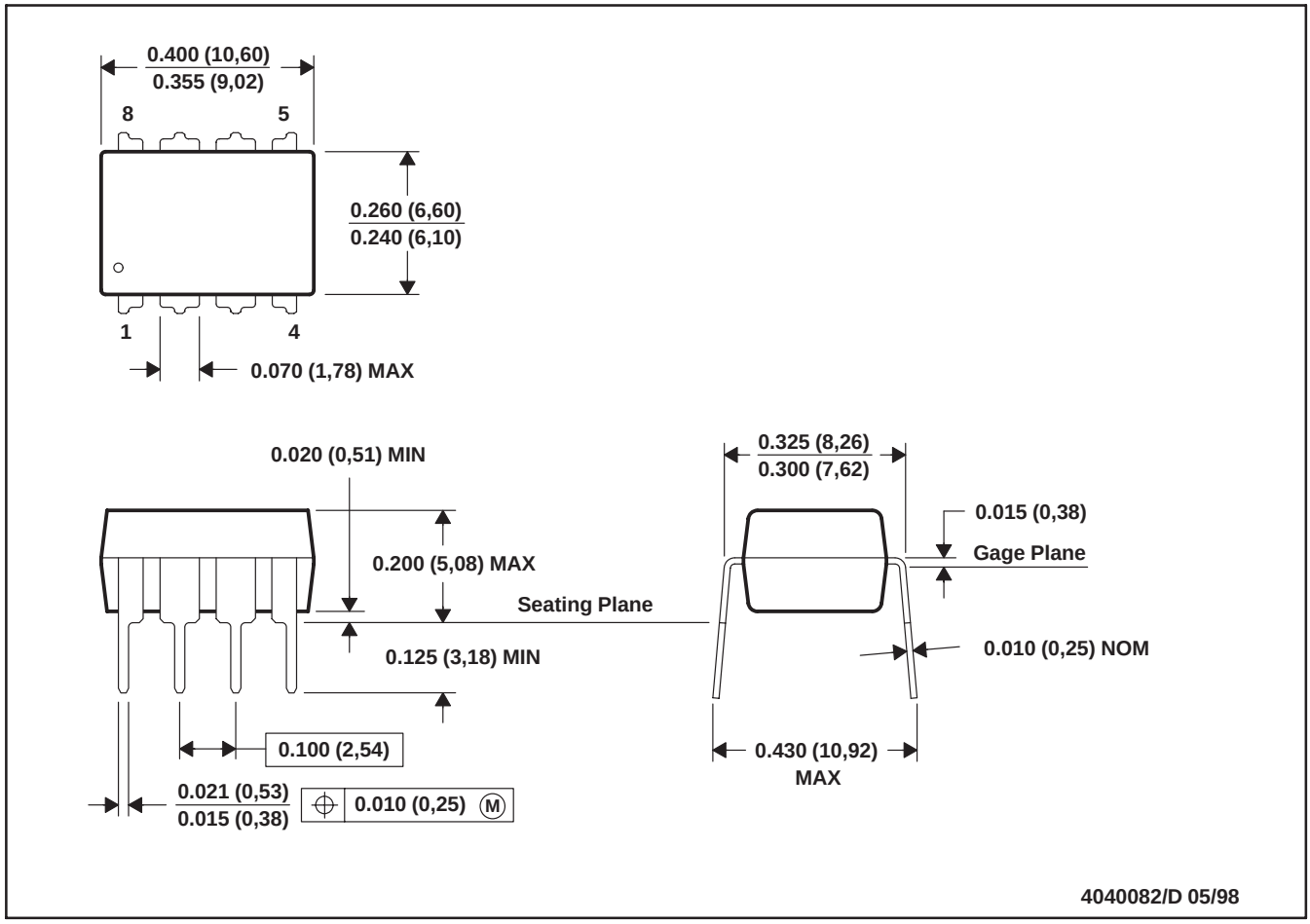
(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

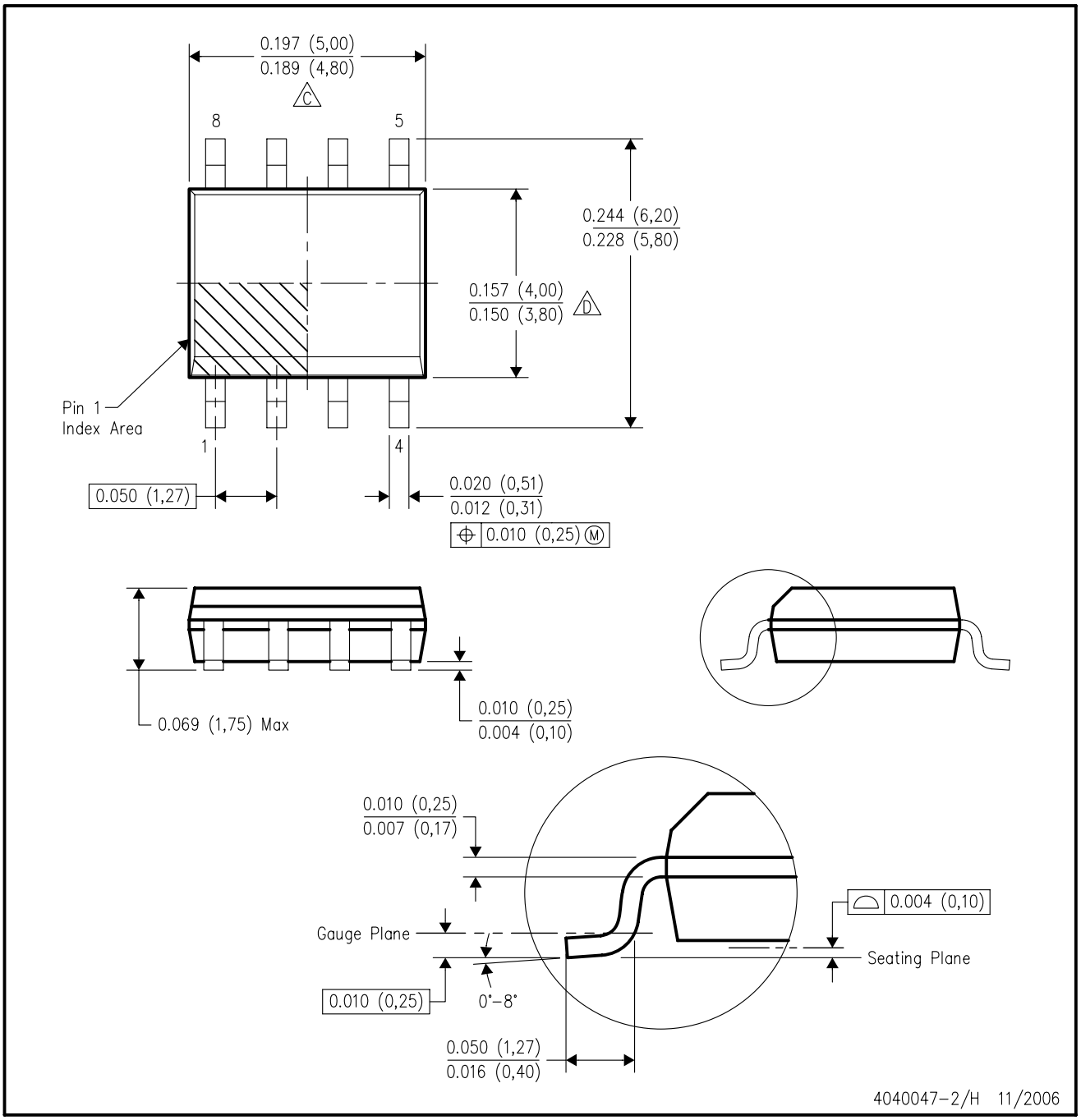
MPDI001A – JANUARY 1995 – REVISED JUNE 1999

P (R-PDIP-T8) **PLASTIC DUAL-IN-LINE**



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-001

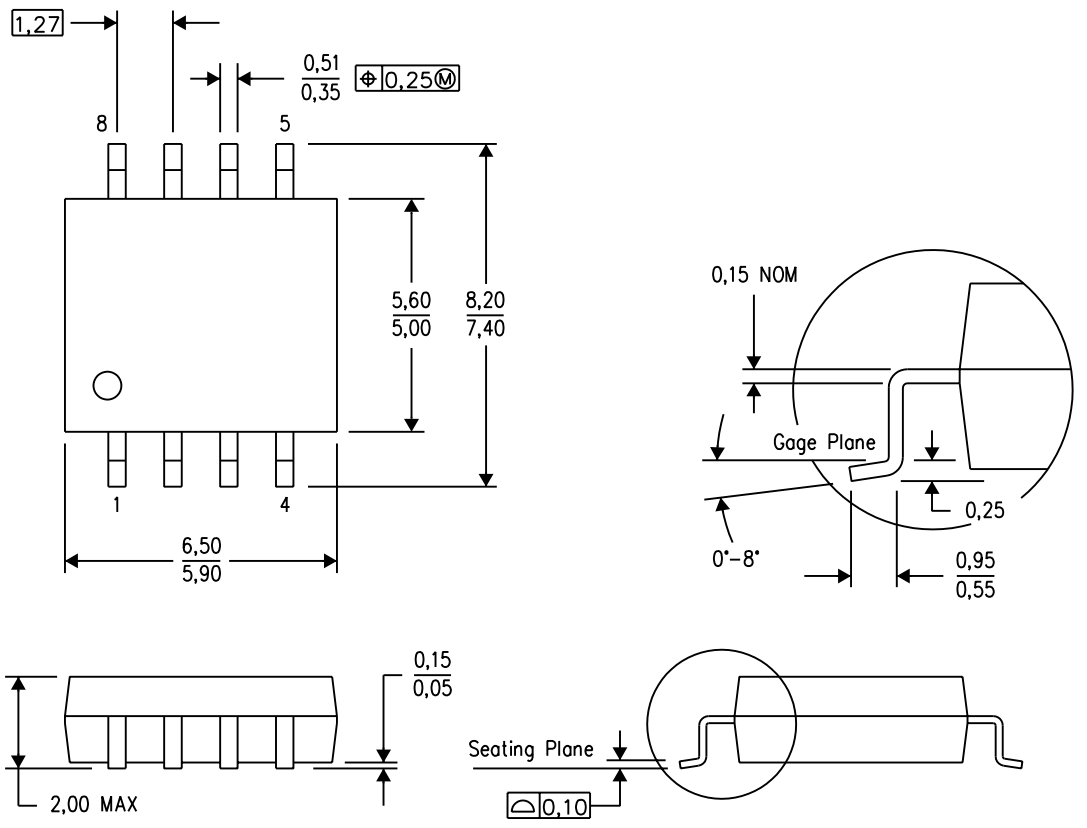
D (R–PDSO–G8) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
E. Reference JEDEC MS–012 variation AA.

MECHANICAL DATA

PS (R-PDSO-G8) **PLASTIC SMALL-OUTLINE PACKAGE**



4040063/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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